

SEAL FOR SURFACE ACOUSTIC WAVE DEVICES

ABSTRACT OF THE DISCLOSURE

One embodiment disclosed relates to a method for sealing an active area of a

5 surface acoustic wave (SAW) device on a wafer. The method includes providing a
sacrificial material over at least the active area of the SAW device, depositing a seal
coating over the wafer so that the seal coating covers the sacrificial material, and
replacing the sacrificial material with a target atmosphere. Another embodiment
disclosed relates to an SAW device sealed at the wafer level (i.e. prior to separation
10 of the die from the wafer). The device includes an active area to be protected, an
electrical contact area, and a lithographically-formed structure sealing at least the active
area and leaving at least a portion of the electrical contact area exposed.